



Material Content Data Sheet



Sales Product Name		BAS 70-02W H6327		Issued		26. September 2017		
MA#		MA000771282						
Package		PG-SCD80-2-1		Weight*		1.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		16	
	noble metal	gold	7440-57-5	0.003	0.16		1589	
	inorganic material	silicon	7440-21-3	0.026	1.36	1.52	13571	15176
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		396	
	non noble metal	chromium	7440-47-3	0.002	0.12		1190	
	non noble metal	copper	7440-50-8	0.744	39.49	39.66	394880	396545
wire	non noble metal	copper	7440-50-8	0.002	0.11	0.11	1090	1090
encapsulation	organic material	carbon black	1333-86-4	0.010	0.52		5224	
	plastics	epoxy resin	-	0.167	8.88		88813	
	inorganic material	silicondioxide	60676-86-0	0.807	42.83	52.23	428391	522428
leadfinish	non noble metal	tin	7440-31-5	0.036	1.91	1.91	19103	19103
plating	noble metal	silver	7440-22-4	0.086	4.57	4.57	45658	45658
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com